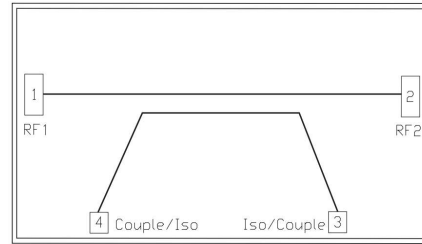


Performance

- Frequency: 6-18GHz
- Coupling: 20dB
- Coupling Flatness: 3.5dB
- Chip size: 2.0*1.3*0.1mm

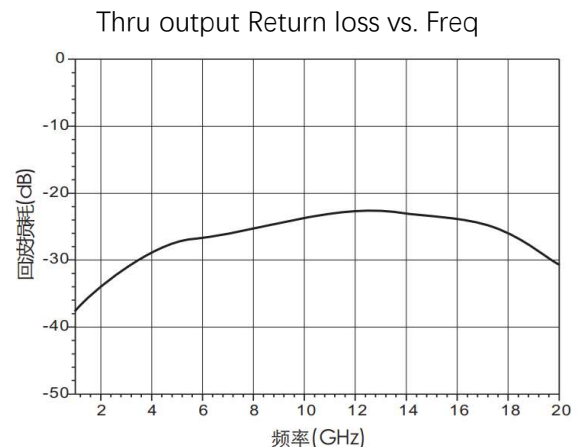
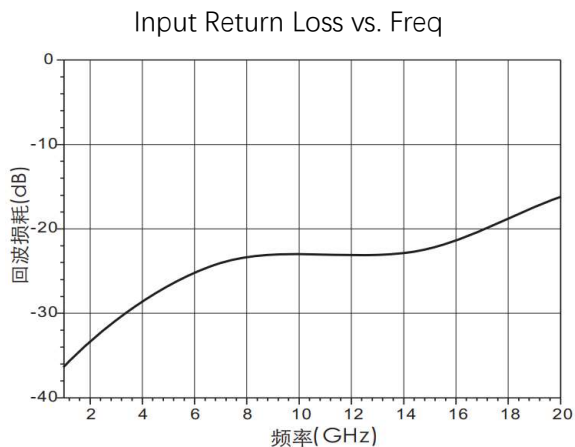
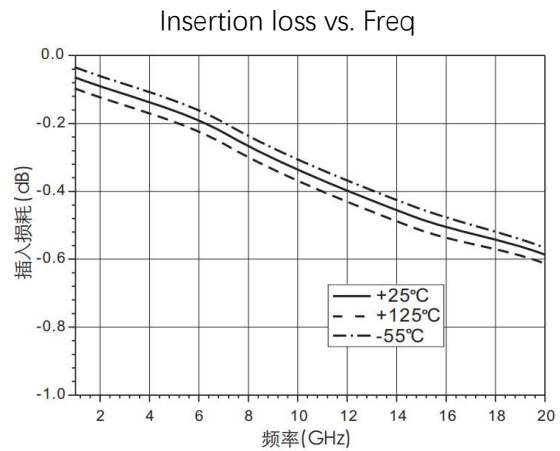
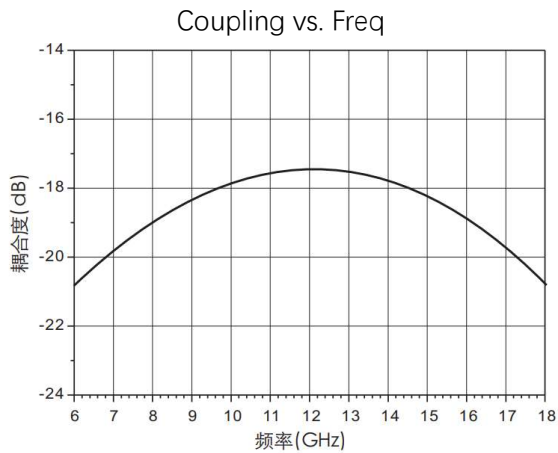
Function Diagram

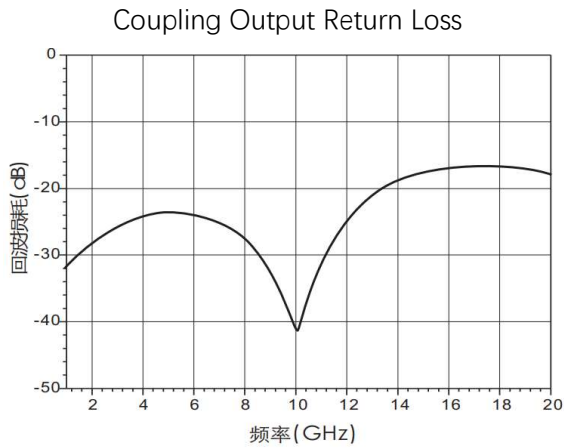


Electrical Specifications (Ta=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range	6-18			GHz
Coupling	17.3	20	20.8	
Insertion Loss	0.3	0.4	0.6	dB
Input Return loss	16	20	-	dB
Thru Output Return loss	22	24	-	dB
Coupling Output Return loss	16	20	-	dB

Test Curves (Die chip + Bonding line test)



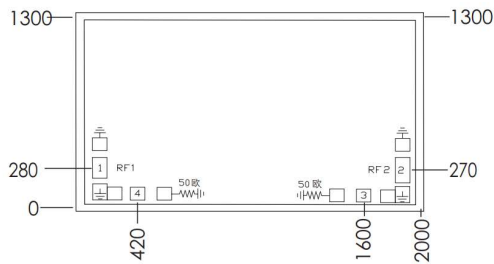


Absolute Rating

Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Max Input Power	5W
Static Protection (HBM)	Class 1A



Outline Size



Note:

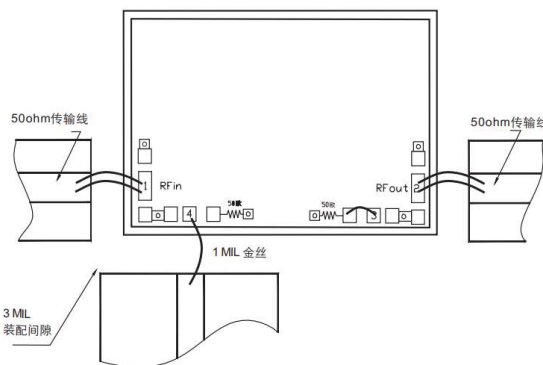
Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated, size: 200*100(um) , 100*100(um)
4. Don't bonding on thru holds
5. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3,4	Couple/ISO	Choose either one as couple output port, another port connect to 50Ω resistor pad
5,6	Load	50Ω resistor pad

Application (Chip left side couple output)



Application (Chip right side couple output)

